OS-201 Solder Stripper

DESCRIPTION

OS-201 SOLDER STRIPPER is the first step in the two-step solder stripping process to prepare solder mask over bare copper (SMOBC) printed circuit boards. OS-201 contains no peroxide, no fluorides, and no chelating agents to complicate waste treatment. Little or no heat is generated by OS-201, so exposed laminate and copper circuitry is not at risk of damage from strong exothermic reactions typical of peroxide-based solder strippers. OS-201 dissolves both tin and lead resulting in less sludging in the bath than most one-step solder strippers. OS-201 provides long bath life and low-use cost.

OPERATING PARAMETERS

Concentration	Undiluted
Temperature	Ambient (60°F to 100°F)
Time	1 minute to 10 minutes

PHYSICAL PROPERTIES AND OPERATING PROCEDURES

Immerse parts to be stripped in undiluted OS-201 at ambient temperature (60 to 100`F) for 1 to 5 minutes at least until vigorous gassing stops. The tin/lead deposit should be completely dissolved leaving the uniform light gray film of copper/tin intermetallic. Remove parts from tank and rinse with clear water. Dip or spray rinsing is acceptable. To remove the intermetallic layer, immerse parts in a suitable second-step solder stripper such as OS-202, OS-203, OS-204, OS-222, OS-235, OS-243, OS-251, or OS-252. Your OS-TECH or Florida CirTech representative can help determine the best product for your application.

Remove parts from the selected second-step stripper as soon as the gray film is dissolved from the surface of the underlying copper. Rinse in clean water. Dip or spray rinsing is acceptable. Dry parts immediately to prevent water spotting. Proceed with solder mask application at once.

CONTROL PROCEDURES

As metal is dissolved in OS-201, the speed of removal of additional metal deposits slowly declines and insoluble metal containing sludge accumulates in the bath. When the performance reaches a point that is no longer acceptable or when sludge accumulation is excessive, the bath should be recharged or rejuvenated. To rejuvenate the bath, allow the sludge to settle and separate the sludge from the clearer OS-201. Add fresh OS-201 to make up volume lost by removal of sludge. Usually rejuvenation of the bath can be performed several times before the bath must be completely recharged.

SAFETY AND STORAGE

PVC, PVDC, Polypropylene, Teflon, and glass may be used in contact with OS-201 solutions.

OS-201 contains strong acids that are corrosive to skin and eyes. Wear eye protection and impervious gloves when handling. In case of skin contact, flush immediately with water. In case of eye contact immediately flush with water for 15 minutes and seek medical attention. Avoid breathing mists and vapors. Harmful if swallowed.